

# **40V N-Channel Trench MOSFET**

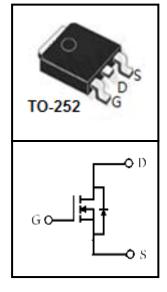
## **FEATURES**

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

### **APPLICATIONS**

- Load Switching
- Hard switched and high frequence circuits
- Uninterruptible power supply





Device Marking and Package Information			
Device	Package	Marking	
CTD04N004	TO-252	CTD04N004	

<b>Absolute Maximum Ratings</b> at T <sub>j</sub> = 25°C unless otherwise noted				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	40	V	
Drain Current-Continuous(Tc=25°C)		140		
Drain Current-Continuous(Tc=100°C)	I <sub>D</sub>	90	Α	
Pulsed Drain Current	I <sub>DM</sub>	560	Α	
Gate Source Voltage	V <sub>GSS</sub>	±20	V	
Single Pulse Avalanche Energy	E <sub>AS</sub>	183	mJ	
Power Dissipation T <sub>C</sub> = 25°C	P <sub>D</sub>	77	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+175	°C	

Thermal Characteristics				
Parameter		Symbol	Value	Unit
Thermal Resistance, Junction-Case	(note1)	$R_{ heta JC}$	2.3	°C/W
Thermal Resistance Junction-Ambient 1 (t≤10s)	(note1)	$R_{ hetaJA}$	62	°C/W



Electrical Characteristics T <sub>j</sub> = 25°C unless otherwise specified							
Para materia			Value				
Parameter	Symbol	Test Conditions		Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	40			V	
Zero Gate Voltage Drain Current		$V_{DS} = 40V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40V, V_{GS} = 0V, T_{J} = 55^{\circ}C$			5		
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Drain Course On Besistance (note2)	Б	$V_{GS} = 10V, I_D = 60A$		3.4	4	mΩ	
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_{D} = 40A$		4.4	6	mΩ	
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V$ ,		4883		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15V$ ,		681			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		525			
Total Gate Charge (4.5V)	$Q_g$			102			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 32V, I_{D} = 80A,$ $V_{GS} = 10V$		21		nC	
Gate-Drain Charge	$Q_{gd}$	1 63 1 1 1		52			
Turn-on Delay Time	t <sub>d(on)</sub>			35			
Turn-on Rise Time	t <sub>r</sub>	$V_{DS} = 20V, V_{GS} = 10V,$		6		ns	
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 3.5\Omega$		120			
Turn-off Fall Time	t <sub>f</sub>			40			
Body Diode Characteristics							
Continuous Body Diode Current	I <sub>S</sub>	T 25.00			140	Δ	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			560	Α	
Body Diode Voltage	V <sub>SD</sub>	TJ = 25°C, ISD = 60A, VGS = 0V	0.4		1	V	

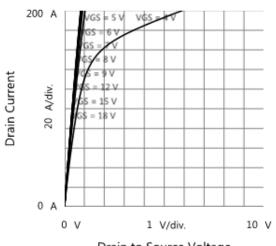
#### **Notes**

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width  $\leq\!300\text{us}$  , duty cycle  $\!\leq\!2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

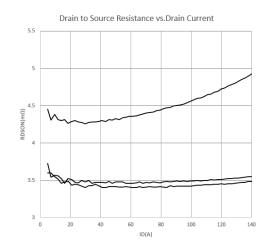


## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

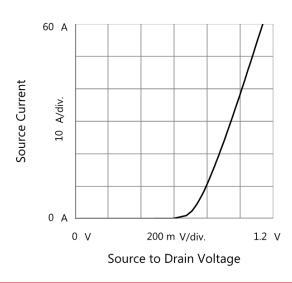
## **Output Characteristics**



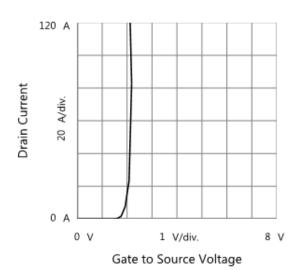
## Drain to Source Voltage



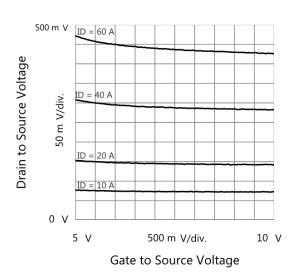
## **Body Diode Forward Characteristics**



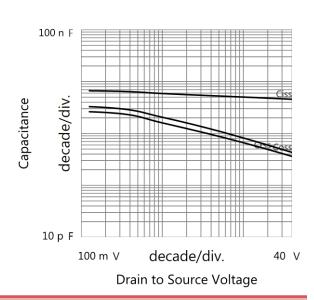
### Transfer Characteristics



Drain to Source Voltage vs. Gate to Source Voltage

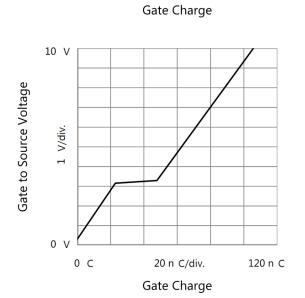


Capacitances





## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



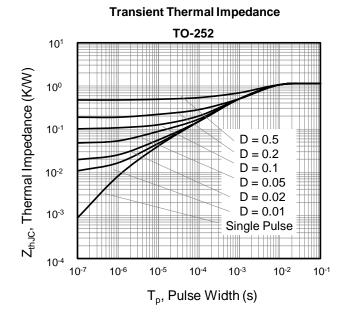




Figure A: Gate Charge Test Circuit and Waveform

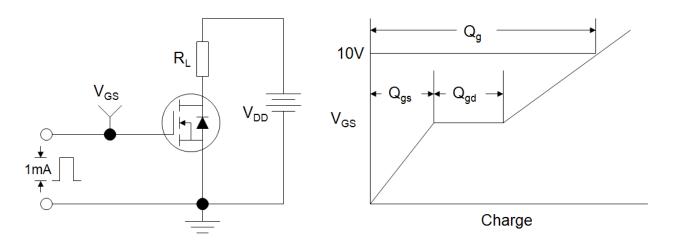


Figure B: Resistive Switching Test Circuit and Waveform

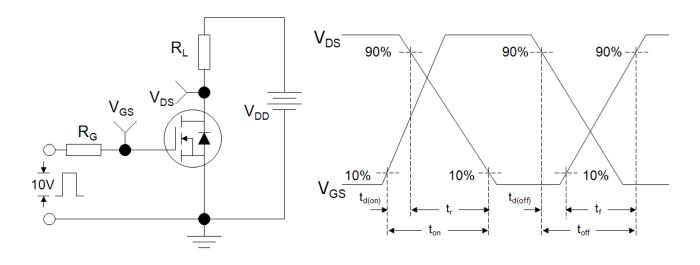
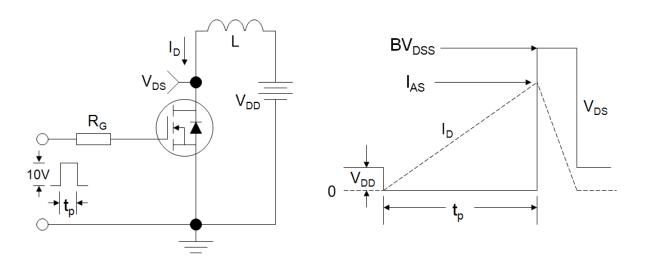
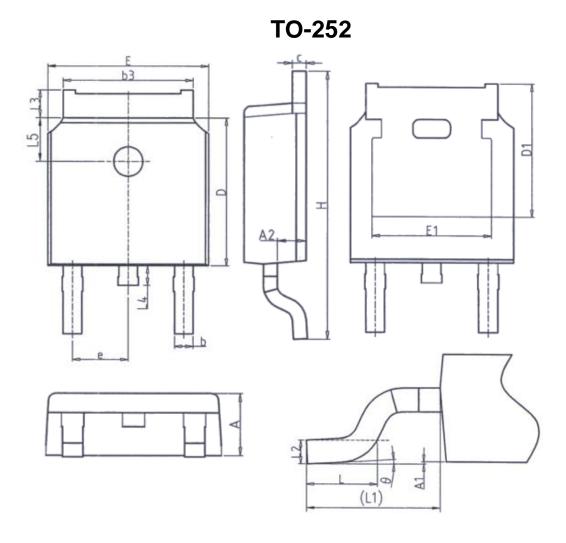


Figure C: Unclamped Inductive Switching Test Circuit and Waveform







Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1. 17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	_		

Unit: mm			
Symbol	Min. Max.		
е	2. 286BSC		
Н	9. 40	10.50	
L	1. 38	1. 75	
L1	2. 90REF		
L2	0. 51BSC		
L3	0.88	1. 28	
L4	_	1.00	
L5	1. 65	1. 95	
θ	0°	8°	



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